

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	"6189203".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 15:30
S2	0	"200301175146"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 10:07
S3	2	"200301175146"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 10:07
S4	1798	361/760.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 15:30
S5	224	S4 and (printed near board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 15:32
S6	136	S5 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 15:50
S7	2	S5 and solder and (lead-free or leadfree)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 15:36
S8	1061	361/767-768.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 15:51

S9	4	361/767-768.ccls. and (printed near board) and solder and (lead-free or leadfree)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 15:54
S10	80	361/767-768.ccls. and (printed near board) and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 15:54
S11	56	(361/767-768.ccls. and (printed near board) and solder) not S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 15:56
S12	897	361/767.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 15:56
S13	239	361/768.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 15:56
S14	1061	S12 S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 15:57
S15	113	361/743.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 15:57
S16	109	361/743.ccls. not (S6 S11)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 16:00

S17	692	174/259.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 16:00
S18	562	174/263.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 16:00
S19	1227	S17 S18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 16:01
S20	747	S19 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 16:01
S21	115	S20 and (printed near board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 16:04
S22	1216	228/180.1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 16:04
S23	820	228/180.1.ccls. and surface	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 16:05
S24	247	228/180.1.ccls. and surface and pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 16:10

S25	419	(228/180.21.ccls. and surface and pad) not S24	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 16:13
S26	13	S25 and (leadfree lead-free)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 16:12
S27	780	(228/180.22.ccls. and surface and pad) not (S24 S26)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 16:13
S28	37	(228/180.22.ccls. and surface and pad and (leadfree lead-free)) not (S24 S26)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 16:14
S29	155	228/180.22.ccls. and surface and pad and spac\$3 and thick\$4 and paste	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 16:20
S30	19	228/180.5.ccls. and surface and pad and spac\$3 and thick\$4 and paste	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 16:21
S31	3	228/178.ccls. and surface and pad and spac\$3 and thick\$4 and paste	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 16:22
S32	9	29/729.ccls. and surface and pad and spac\$3 and thick\$4 and paste	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 16:23

S33	10	(US "6229711" B1 US "6787711" B2 US "6760227" B2 US "6734665" B2 US "20040062015" A1 US "6710263" B2 US "20030081393" A1 US "6480394" B1 US "6418030" B1 US "5870289" A US "5818698" A US "5400221" A US "5122929" A US "5525763" A US "6722028" B2 US "6642485" B2 US "6629633" B1 US "5729896" A) and (copper adj pad) and chip and connector and shield and organic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 16:54
S34	0	(mounting with surface) and (copper adj pad) and (chip component) and connector and (EMI RFI with shield) and (solder with joint) and (lead-free leadfree unlead\$2) and coat\$3 and organic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 10:12
S35	0	(printed near1 board) and ((mount\$3 with surface) or (SMT))and ((copper with pad or land))and ((microchip or chip or component) with connector) and (EMI or RFI with shield) and (solder\$3 with joint) and (lead-free or leadfree or unlead\$2) and coat\$3 and organic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 10:21
S36	3	(printed near1 board) and ((mount\$3 with surface) or (SMT))and ((copper with pad or land))and ((microchip or chip or component) with connector) and (solder\$3 with joint) and (lead-free or leadfree or unlead\$2) and coat\$3 and organic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 10:46
S37	3	(printed near1 board) and surface and ((mount\$3 adj surface) or (SMT))and (copper adj(pad or land))and ((microchip or chip or component) with connector) and (solder\$3 with joint) and (lead-free or leadfree or unlead\$2) and coat\$3 and organic and paste	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 10:52
S38	3	(printed near1 board) and surface and ((mount\$3 adj surface) or (SMT)) and (copper adj(pad or land))and ((microchip or chip or component) with connector) and solder\$3 and paste and (lead-free or leadfree or unlead\$2) and coat\$3 and organic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 10:54

S39	3	(printed near1 board) and ((mount\$3 adj surface) or SMT) and (copper adj(pad or land))and ((microchip or chip or component) with connector) and solder\$3 and paste and (lead-free or leadfree or unlead\$2) and coat\$3 and organic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 10:56
S40	3	(printed near1 board) and ((mount\$3 adj surface) or SMT) and (copper adj(pad or land)) and solder\$3 and paste and (lead-free or leadfree or unlead\$2) and coat\$3 and organic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 10:58
S41	3	(printed near1 board) and ((mount\$3 adj surface) or SMT) and (copper adj(pad or land)) and solder\$3 and (lead-free or leadfree or unlead\$2) and coat\$3 and organic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 10:58
S43	10	((mount\$3 adj surface) or SMT) and (copper adj(pad or land)) and solder\$3 and (lead-free or leadfree or unlead\$2)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:15
S44	11975232	"10" not S37	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:00
S45	0	("2005/0157476").URPN.	USPAT	OR	ON	2005/08/30 11:06
S46	0	("2004/0118586").URPN.	USPAT	OR	ON	2005/08/30 11:07
S47	8	("20030089617"   "5698160"   "5716663"   "5863355"   "5955141"   "6066197"   "6457632"   "6592020").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/30 11:07
S48	0	("6902102").URPN.	USPAT	OR	ON	2005/08/30 11:11
S49	13	(("5634268") or ("4967950") or ("5597469") or ("5238176") or ("5251806") or ("5130779") or ("5898992")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/30 11:17
S50	181	361/771.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:21

S51	493992	"174"/("257", "261").ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:21
S52	493992	"174"/("257", "261").ccls. and (mount\$3 adj surface)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:22
S53	806	174/257.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:22
S54	1	174/257.ccls. and (mount\$3 adj surface) and (copper adj (pad or land))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:23
S55	35	174/257.ccls. and (mount\$3 adj surface)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:23
S56	170	174/261.ccls. and (mount\$3 adj surface)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:24
S57	243	361/760.ccls. and (mount\$3 adj surface)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:25
S58	172	361/760.ccls. and (mount\$3 adj surface) and (pad or land)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:25

S59	170	S58 not (S55)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:28
S60	249	361/763.ccls. not S59	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:29
S61	29	361/763.ccls. not S59 and (mount\$3 adj surface) and (pad or land)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:33
S62	39	361/772.ccls. not S59 and (mount\$3 adj surface) and (pad or land or bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:37
S63	39	S62 not S61	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:34
S64	16	361/779.ccls. not S59 and (mount\$3 adj surface) and (pad or land or bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:42
S65	50	29/841.ccls. and (mount\$3 adj surface) and (pad or land or bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:43
S66	0	(mount\$3 with surface) and solder and paste and thick\$4 and organic and rosin and stencil and (pad or land or bump) and spac\$3 and (microchip or chip) and conector and (discrete with component)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:55

S67	0	(mount\$3 with surface) and solder and paste and thick\$4 and organic and rosin and (pad or land or bump) and spac\$3 and (microchip or chip) and connector and component	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:56
S68	13	(mount\$3 with surface) and solder and paste and thick\$4 and organic and rosin and (pad or land or bump) and spac\$3 and (microchip or chip) and connector and component	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:59
S69	2439	(mount\$3 with surface) and (EMI or RFI) and shield	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:59
S70	1855	(mount\$3 with surface) and (EMI or RFI) and shield and component	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 12:00
S71	839	(mount\$3 with surface) and (EMI or RFI) and shield and component and (pad or land or bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 12:00
S72	400	(mount\$3 with surface) and (EMI or RFI) and shield and component and (pad or land or bump) and chip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 12:00
S73	64	(mount\$3 with surface) and (EMI or RFI) and shield and component and (pad or land or bump) and chip and copper and organic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 12:01
S74	5	(mount\$3 with surface) and (EMI or RFI) and shield and component and (pad or land or bump) and solder\$3 and (lead\$free or unlead\$2)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 12:01

S75	3	(printed near1 board) and ((mount\$3 adj surface) or SMT) and (copper adj(pad or land)) and solder\$3 and (lead-free or leadfree or unlead\$2)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 13:44
S76	16147309	JP "2002004185"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 13:45
S77	1	"2002004185".pran.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 13:46

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	32332	benzimidazole	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 08:06
S2	87	benzimidazole and (printed near board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:09
S3	73	benzimidazole and (printed near board) and coat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:09
S4	30	benzimidazole and (printed near board) and coat\$3 and (pad or land)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:19
S5	7	S4 and (lead\$free or unlead\$2) and organic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:25
S6	2	"6457632".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:27
S7	1	solder\$3 and (non adj step adj down adj stencil)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:28
S8	4096	solder\$3 and (stencil)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:29

S9	1	solder\$3 and (non with step with down with stencil)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:29
S10	20	solder\$3 and (step with down with stencil)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:37
S11	6	solder\$3 and (step adj down adj stencil)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:37
S12	1	"20050157476"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 09:19
S13	39357	benzotriazole	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 09:19
S14	32332	benzimidazole	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 09:21
S15	.32	benzimidazole and (copper adj pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 08:06